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PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-293938

(43)Date of publication of application : 11.11.1997

(51)Int.CI.

H05K 1/02

(21)Application number : 08-221503

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(22)Date of filing : 22.08.1996

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(30)Priority

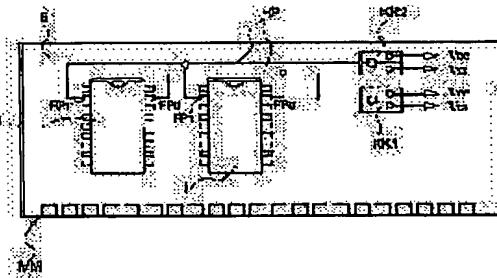
Priority number : 08 37764 Priority date : 26.02.1996 Priority country : JP

(54) MEMORY MODULE AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To arbitrarily switch the function and the word structure of a semiconductor device at a package outside part.

SOLUTION: In a memory module MM, a function switching devices KK1 and KK2, with which the function switching signals inputted to function switching pins FP0 and FP1 of a memory 1 are arbitrarily switched, are provided on a module wiring board 5. The function switching signals are arbitrarily switched from nonconnection, source voltage Vcc or grounding potential Vss by the function switching devices KK1 and KK2, the function switching signals are collectively inputted to all the mounted memories 1, and the function consisting of a read-out system and a fresh cycle is switched and arbitrarily set.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

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[Date of registration]

[Number of appeal against examiner's decision of rejection]

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[Date of extinction of right]

6 モジュール配線基板 (専用プリント配線基板)

BP ボンディングハット

BP 0～BP 3 ボンディングハッド

FPP0, FPP1 機能切り換え用ピン (機能切り換え用)

外部端子)

FPP2, FPP3 ワード線切り換え用ピン (ワード線
成切り換え用外部端子)

KK1, KK2 機能切り換え手段

WL1, WL2, WL3 ワード線切り換え手段

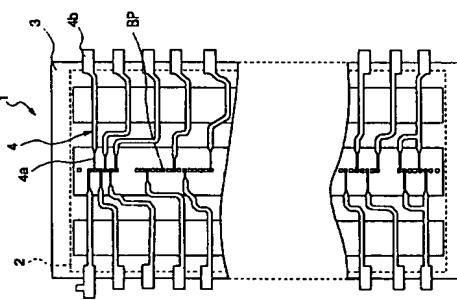
L1, L2, L3 ランド (第1の接続部)

L2, L3 ランド (第2の接続部)

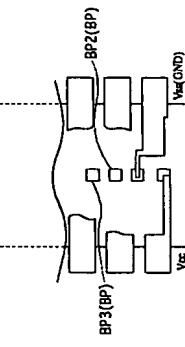
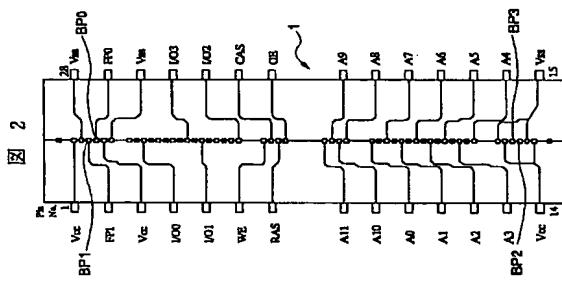
L3 ランド (第3の接続部)

L 4	ランド (第1の接続部)
L 5	ランド (第2の接続部)
L 6	ランド (第3の接続部)
MM	メモリモジュール
MT	モジュールI/O端子
JC	導通チップ (導通手段)
HP	配線ハーネン
HP 1	配線ハーネン (ワード構成設定)
HP 2	配線ハーネン (機能設定配線)
10 W	ボンディングワイヤ
Vcc	電源電圧
Vss	グランド電位

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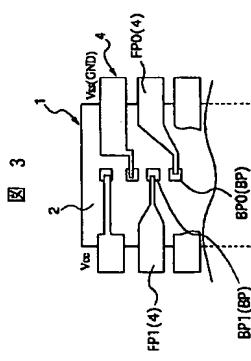


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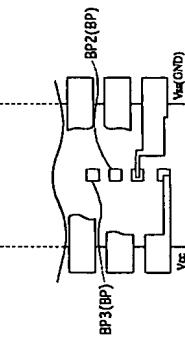
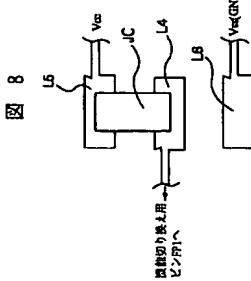


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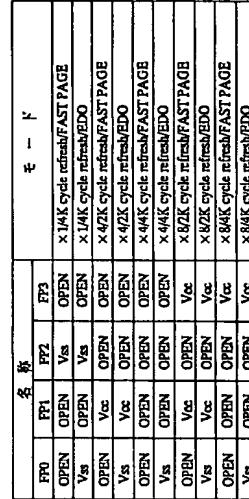
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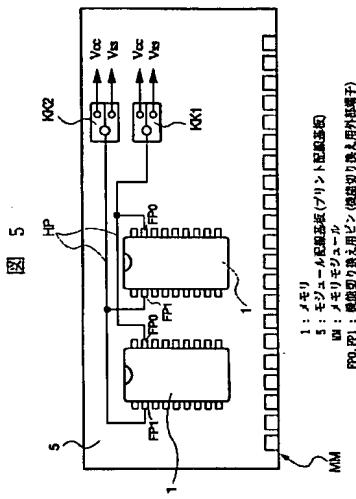
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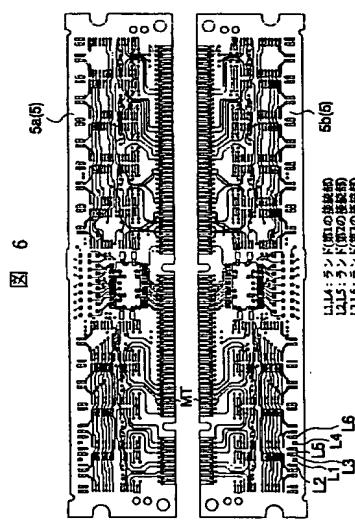


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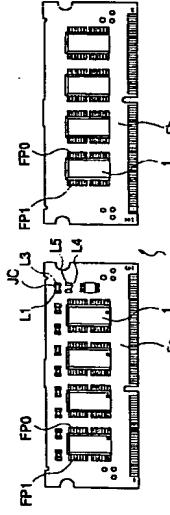


〔図6〕

〔図6〕

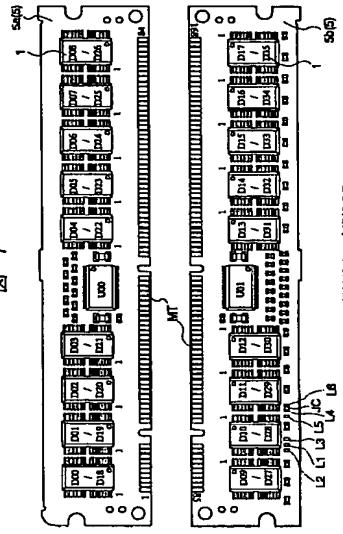


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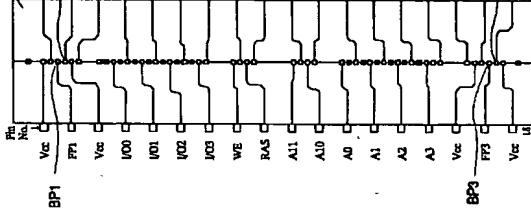


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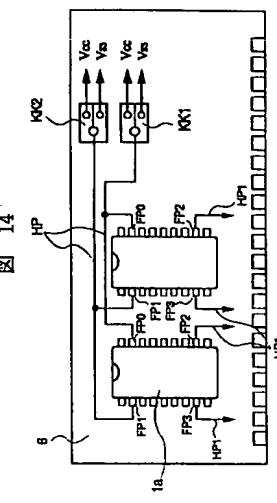
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〔図13〕

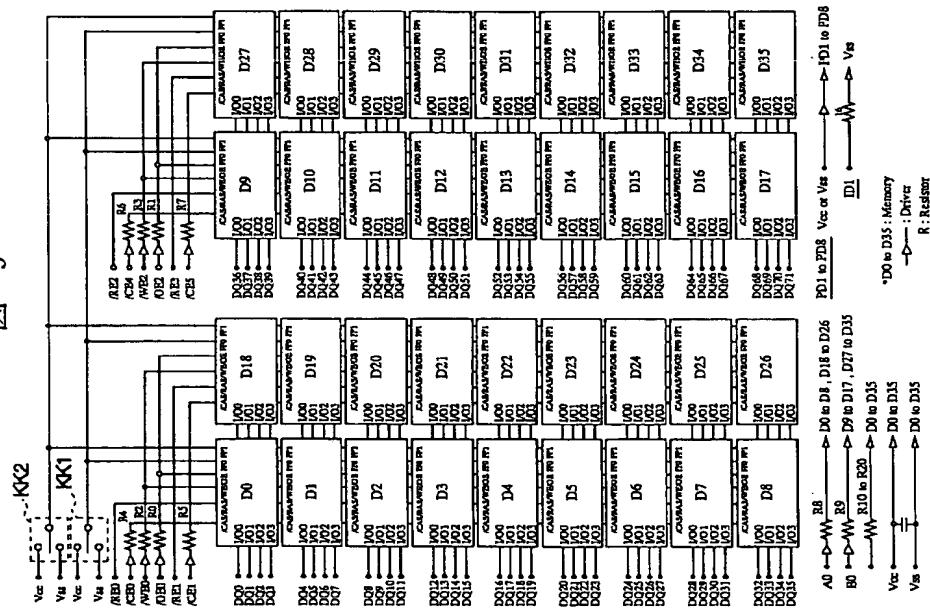


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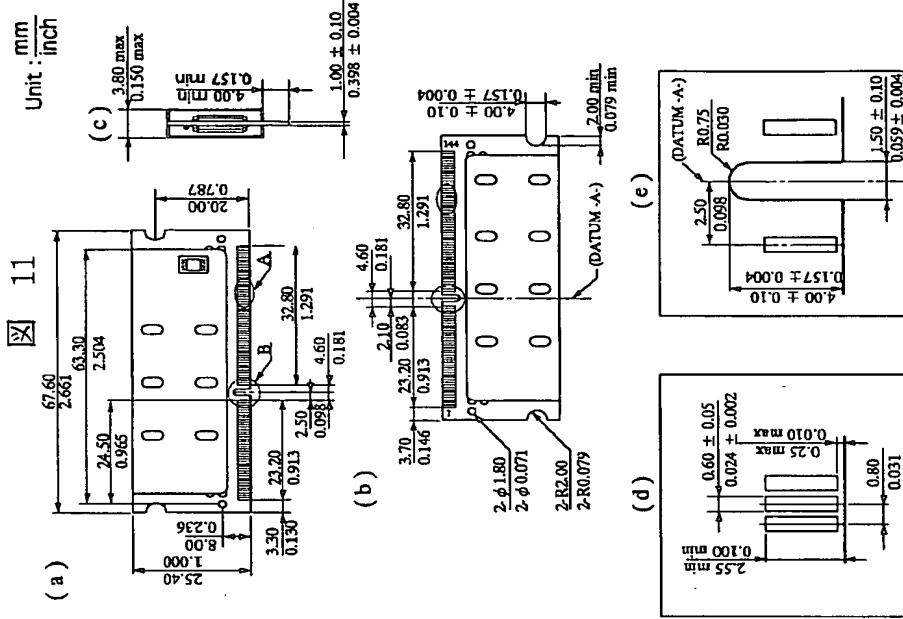


〔図14〕

[図9]

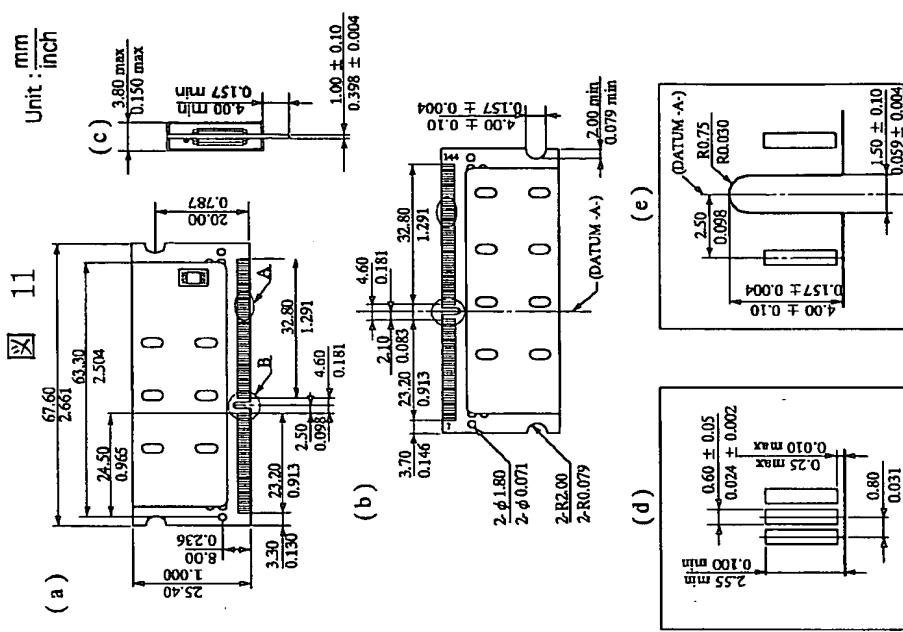


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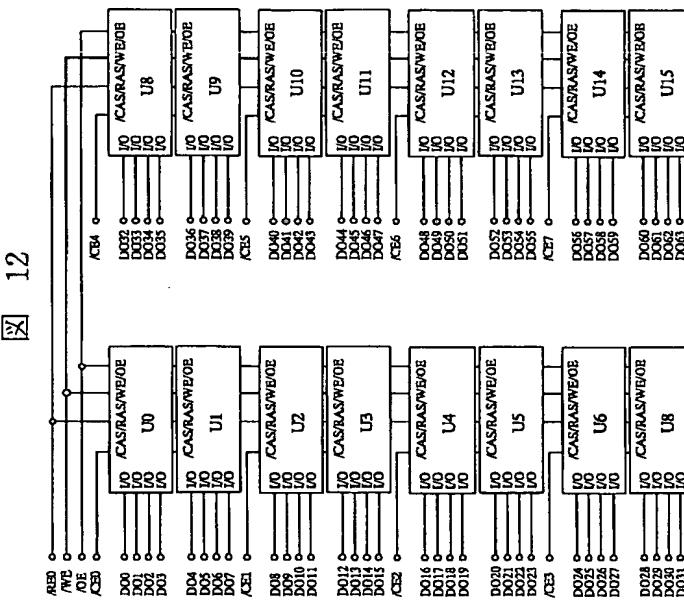


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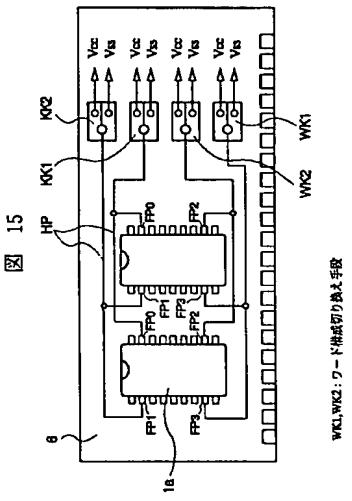


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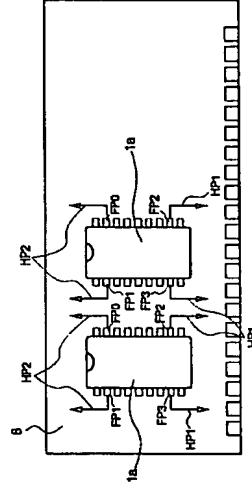


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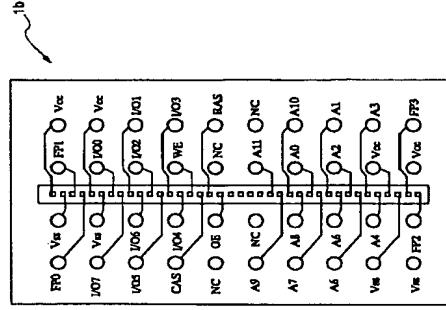


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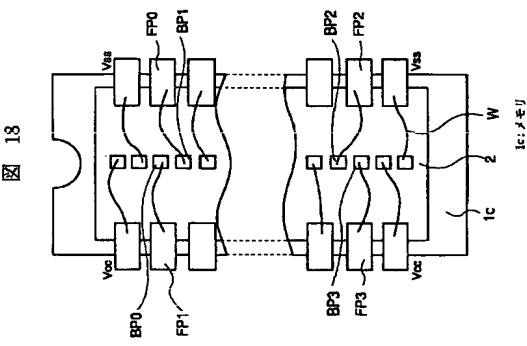
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FP1	4nd	2nd

A 3D coordinate system with three axes: V_x (vertical), V_y (depth), and V_z (horizontal). The V_x axis points upwards, V_y points towards the viewer, and V_z points to the right.

[図17]



[四] 181



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フロントページの続き

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